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From: Charles A. Brill
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-4379**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

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NAME OF INVENTOR(S): Mezenner	
RECEIPT DATE & SERIAL NO.: Application No.: 10/749,277	
TITLE OF INVENTION: VIA ADHESION IN MULTILAYER MEMS STRUCTURE	
Filing Date: 31 December 2003	
TI FILE NO.: TI-33824	DEPOSIT ACCT. NO.: 20-0668
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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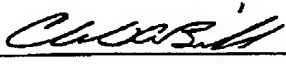
Docket No. TI-33824

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AMENDMENT

11 April 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

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	11 April 2005
Charles A. Brill	Date

Dear Sir:

In response to the Examiner's Action mailed 10 January 2005, applicant amends as follows:

Amendment - Page 1